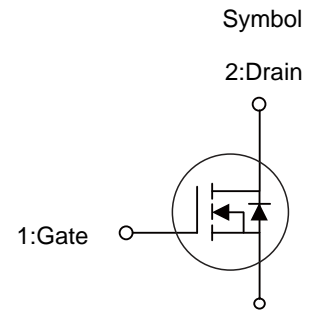


■ PRODUCT CHARACTERISTICS

V <sub>DSS</sub>	-100V
R <sub>DS(ON)</sub> Typ(@V <sub>GS</sub> =-10V)	87mΩ
R <sub>DS(ON)</sub> Typ(@V <sub>GS</sub> =-4.5V)	93mΩ
I <sub>D</sub>	-26A

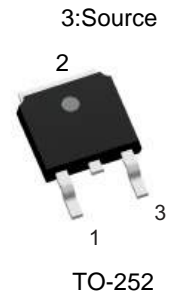


■ APPLICATIONS

- \* Electronic lamp ballasts based on half bridge
- \* Load Switching, Quick/Wireless Charge.
- \* Motor Driving

■ FEATURE

- \* Low Gate Charge
- \* Pb-Free Lead Plating



■ ORDER INFORMATION

Order Codes		Package	Packing
Halogen-Free	Halogen		
N/A	MOT26P10D	TO-252	2500 pieces/Reel

■ ABSOLUTE MAXIMUM RATINGS(T<sub>A</sub>=25°C, unless otherwise specified)

Parameter	Symbol	Ratings	Unit
Drain-Source Voltage	V <sub>DSS</sub>	-100	V
Gate-Source Voltage	V <sub>GSS</sub>	±20	V
Drain Current Continuous(@V <sub>GS</sub> =-10V, T <sub>A</sub> =25°C)	I <sub>D</sub>	-26	A
Drain Current Pulsed	I <sub>DM</sub>	-104	A
Avalanche Energy	E <sub>AS</sub>	156	mJ
Power Dissipation	P <sub>D</sub>	102	W
Junction Temperature	T <sub>J</sub>	+150	°C
Storage Temperature	T <sub>STG</sub>	-55~ +150	°C

■ THERMAL CHARACTERISTICS

Parameter	Symbol	Typ	Unit
Junction to Case	R <sub>thJC</sub>	1.22	°C/W

**■ ELECTRICAL CHARACTERISTICS** ( $T_C=25^\circ\text{C}$ , unless otherwise noted)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Off characteristics						
Drain to Source Breakdown Voltage	$V_{DSS}$	$V_{GS}=0V, I_D=-250\mu A$	-100	-	-	V
Drain to Source Leakage Current	$I_{DSS}$	$V_{DS}=-100V, V_{GS}=0V$	-	-	-1	$\mu A$
Gate to Source Forward Leakage	$I_{GSS(F)}$	$V_{GS}=+20V, V_{DS}=0V$	-	-	100	nA
Gate to Source Reverse Leakage	$I_{GSS(R)}$	$V_{GS}=-20V, V_{DS}=0V$	-	-	-100	nA
On characteristics						
Drain to Source On-Resistance	$R_{DS(ON)}$	$V_{GS}=-10V, I_D=-10A$	-	87	103	m $\Omega$
		$V_{GS}=-4.5V, I_D=-8A$	-	93	117	m $\Omega$
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{DS}=V_{GS}, I_D=-250\mu A$	-1	-1.6	-2.5	V
Dynamic characteristics						
Gate capacitance	$R_g$	$V_{GS}=0V, V_{DS}=0V, f=1.0\text{MHz}$	-	5.3	-	$\Omega$
Forward Transconductance	$g_{fs}$	$V_{DS}=-10V, I_D=-3A$	8	-	-	S
Input Capacitance	$C_{iss}$	$V_{DS}=-30V, V_{GS}=0V$ $f=1.0\text{MHz}$	-	3700	-	pF
Output Capacitance	$C_{oss}$		-	84	-	pF
Reverse Transfer Capacitance	$C_{rss}$		-	80	-	pF
Resistive Switching Characteristics						
Turn-on Delay Time	$t_{d(ON)}$	$V_{GS}=-10V, V_{DS}=-50V,$ $I_D=-10A, R_G=2.7\Omega$	-	8	-	ns
Rise Time	$t_r$		-	27	-	ns
Turn-off Delay Time	$t_{d(OFF)}$		-	115	-	ns
Fall Time	$t_f$		-	77	-	ns
Total Gate Charge	$Q_g$	$I_D=-10A, V_{DS}=-50V$ $V_{GS}=-10V$	-	53	-	nC
Gate to Source Charge	$Q_{gs}$		-	12	-	nC
Gate to Drain("Miller") Charge	$Q_{gd}$		-	10	-	nC
Source-Drain Diode Characteristics						
Continuous Source Current(Body Diode)	$I_S$		-	-	-26	A
Maximum Pulsed Current(Body Diode)	$I_{SM}$		-	-	-104	A
Diode Forward Voltage	$V_{SD}$	$I_{SD}=-1A, V_{GS}=0V$	-	-0.74	-1.2	V
Reverse Recovery Time	$t_{rr}$	$I_{SD}=-20A, T_J=25^\circ\text{C}$ $di/dt=100A/\mu s$	-	36	-	ns
Reverse Recovery Charge	$Q_{rr}$		-	40	-	nC

■ TYPICAL CHARACTERISTICS

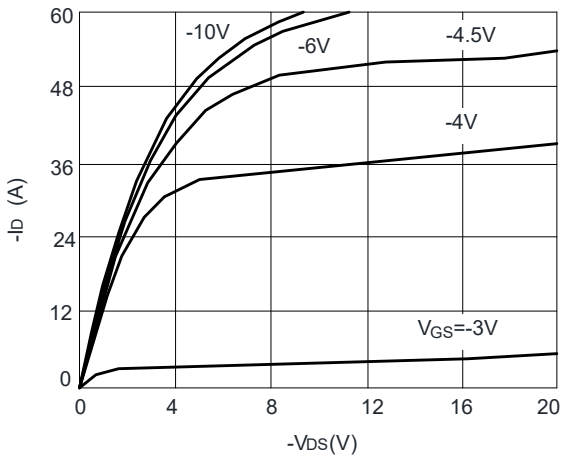


Figure 1: Output Characteristics

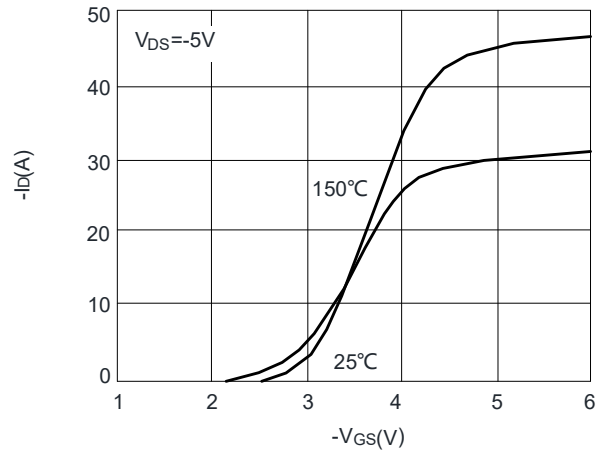


Figure 2: Transfer Characteristics

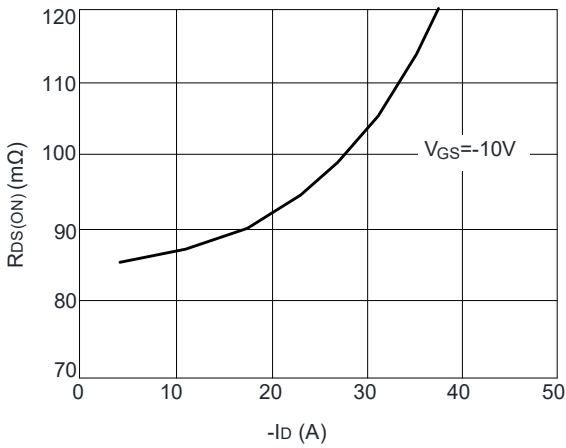


Figure 3: On-resistance vs. Drain Current

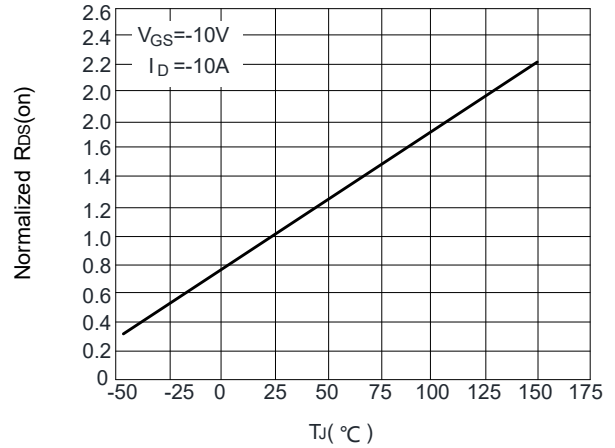


Figure 4: R\_DS(on) vs. Temperature

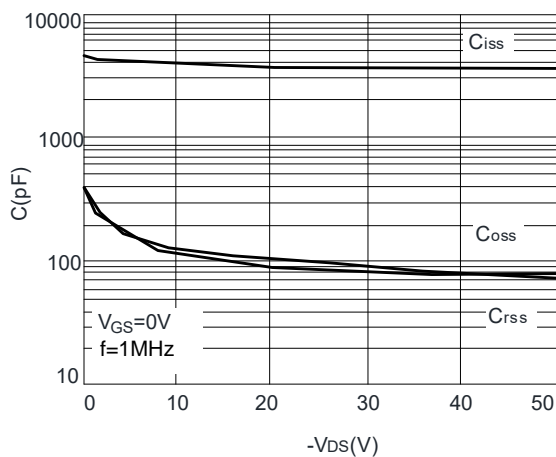


Figure 5: capacitance Characteristics

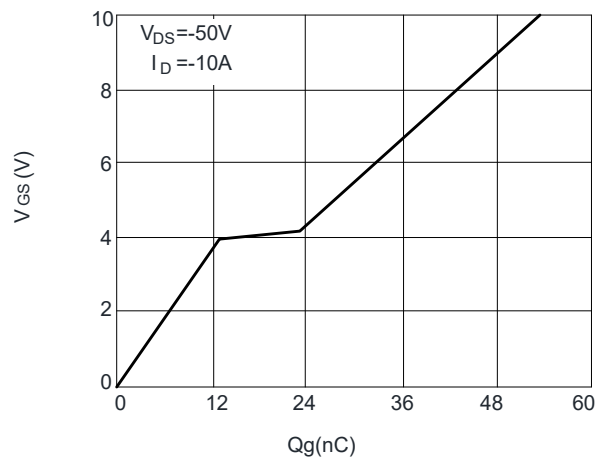


Figure 6: Gate Charge Characteristics

■ TYPICAL CHARACTERISTICS(Cont.)

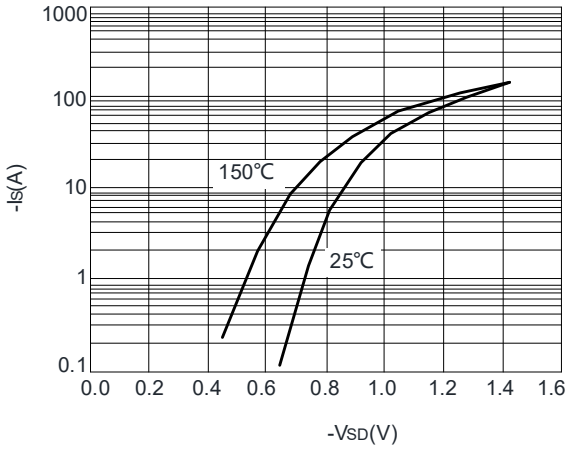


Figure 7: Body Diode Characteristics

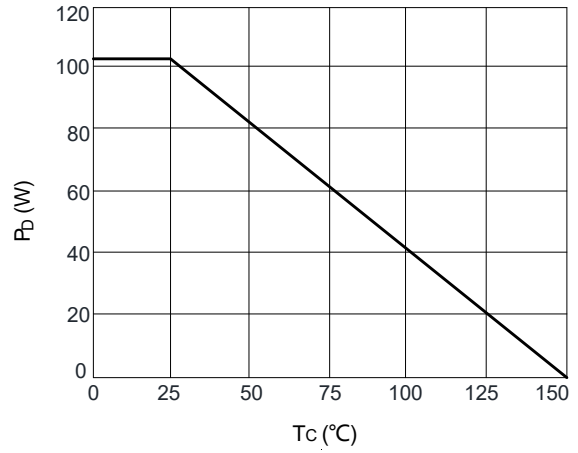


Figure 8: Power De-rating

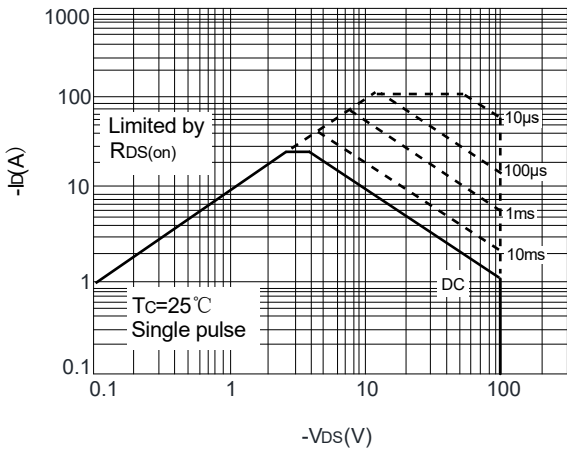


Figure 9: Safe Operation Area

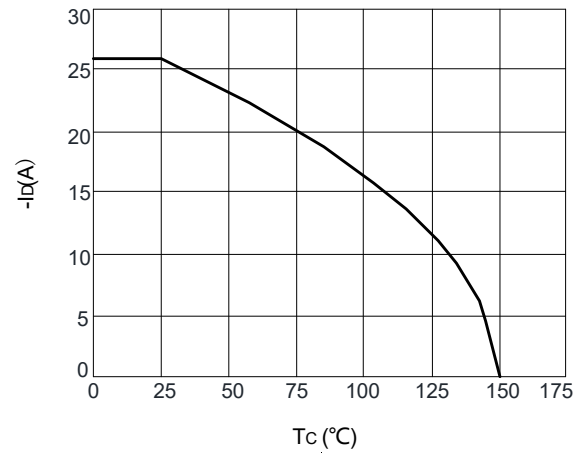


Figure 10: Current De-rating

■ TO-252 PACKAGE OUTLINE DIMENSIONS

